

VS-HFA16PA60CPbF, VS-HFA16PA60C-N3

Vishay Semiconductors

| ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified) | | | | | | | |
|--|-----------------|--|------------|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS |
| Cathode to anode breakdown voltage | V _{BR} | Ι _R = 100 μΑ | | 600 | - | - | |
| Maximum forward voltage | | I _F = 8.0 A | See fig. 1 | = | 1.4 | 1.7 | V |
| | V_{FM} | I _F = 16 A | | = | 1.7 | 2.1 | |
| | | I _F = 8.0 A, T _J = 125 °C | | = | 1.4 | 1.7 | |
| Maximum reverse | , | $V_R = V_R$ rated | - | 0.3 | 5.0 | | |
| leakage current | I _{RM} | T _J = 125 °C, V _R = 0.8 x V _R rated | See fig. 2 | = | 100 | 500 | μΑ |
| Junction capacitance | C _T | V _R = 200 V See fig. 3 | | = | 10 | 25 | pF |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | | - | 8.0 | - | nH |

| DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified) | | | | | | | | | |
|---|---------------------------|--|--|------|------|-------|-----------|--|--|
| PARAMETER | SYMBOL | TEST CO | MIN. | TYP. | MAX. | UNITS | | | |
| Reverse recovery time See fig. 5, 6 and 16 | t _{rr} | $I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ | | - | 18 | - | | | |
| | t _{rr1} | T _J = 25 °C | I _F = 8.0 A dI _F /dt = 200 A/μs V _R = 200 V | - | 37 | 55 | ns | | |
| | t _{rr2} | T _J = 125 °C | | - | 55 | 90 | | | |
| Peak recovery current See fig. 7 and 8 | I _{RRM1} | T _J = 25 °C | | - | 3.5 | 5.0 | A nC A/μs | | |
| | I _{RRM2} | T _J = 125 °C | | - | 4.5 | 8.0 | | | |
| Reverse recovery charge See fig. 9 and 10 | Q _{rr1} | T _J = 25 °C | | - | 65 | 138 | | | |
| | Q _{rr2} | T _J = 125 °C | | - | 124 | 360 | | | |
| Peak rate of fall recovery current during t _b See fig. 11 and 12 | dI _{(rec)M} /dt1 | T _J = 25 °C | | - | 240 | - | | | |
| | dI _{(rec)M} /dt2 | T _J = 125 °C | | - | 210 | - | | | |

| THERMAL - MECHANICAL SPECIFICATIONS | | | | | | | | |
|---|-------------------|--|--------------|------|------------|------------------------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | | |
| Lead temperature | T _{lead} | 0.063" from case (1.6 mm) for 10 s | - | - | 300 | °C | | |
| Junction to case, single leg conducting |) | | - | - | 3.5 | | | |
| Junction to case, both leg conducting | R _{thJC} | | - | - | 1.75 | K/W | | |
| Thermal resistance, junction to ambient | R _{thJA} | Typical socket mount | - | - | 40 | TV VV | | |
| Thermal resistance, case to heatsink | R _{thCS} | Mounting surface, flat, smooth and greased | i | 0.25 | - | | | |
| Weight | | | - | 6.0 | - | g | | |
| vveignt | | | - | 0.21 | - | oz. | | |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | | |
| Marking device | | Case style TO-247AC (JEDEC) | HFA16PA60C | | | | | |



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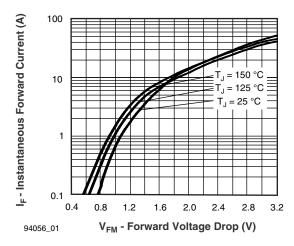


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

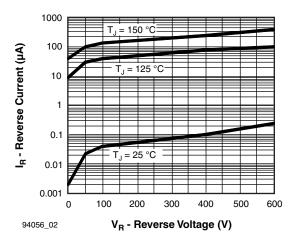


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

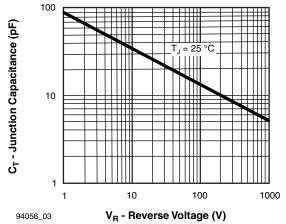


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

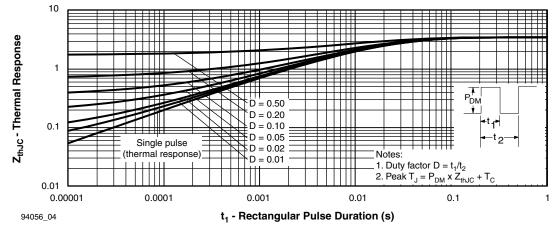


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

500

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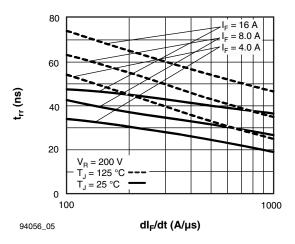


Fig. 5 - Typical Reverse Recovery Time vs. dl_E/dt (Per Leg)

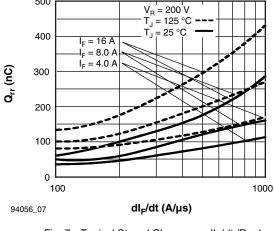


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

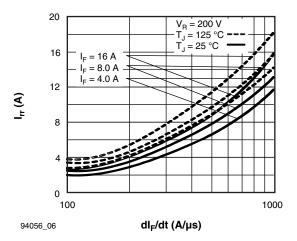


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

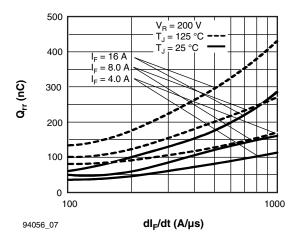


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

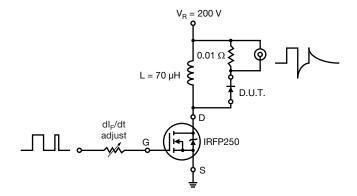
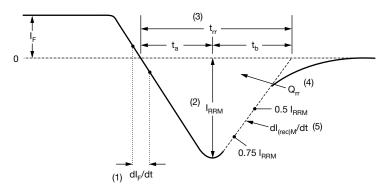


Fig. 9 - Reverse Recovery Parameter Test Circuit

VS-HFA16PA60CPbF, VS-HFA16PA60C-N3

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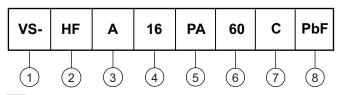


- (1) dl_F/dt rate of change of current through zero crossing
- (4) \boldsymbol{Q}_{rr} area under curve defined by \boldsymbol{t}_{rr} and \boldsymbol{I}_{RRM}
- (2) I_{RRM} peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (5) dl_{(rec)M}/dt peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- Vishay Semiconductors product
- 2 HEXFRED® family
- 3 Electron irradiated
- Current rating (16 = 16 A)
- **5** PA = TO-247AC
- 6 Voltage rating: (60 = 600 V)
- Circuit configuration

C = Common cathode

8 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

| ORDERING INFORMATION (Example) | | | | | | | |
|--------------------------------|------------------|------------------------|-------------------------|--|--|--|--|
| PREFERRED P/N | QUANTITY PER T/R | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION | | | | |
| VS-HFA16PA60CPbF | 25 | 500 | Antistatic plastic tube | | | | |
| VS-HFA16PA60C-N3 | 25 | 500 | Antistatic plastic tube | | | | |

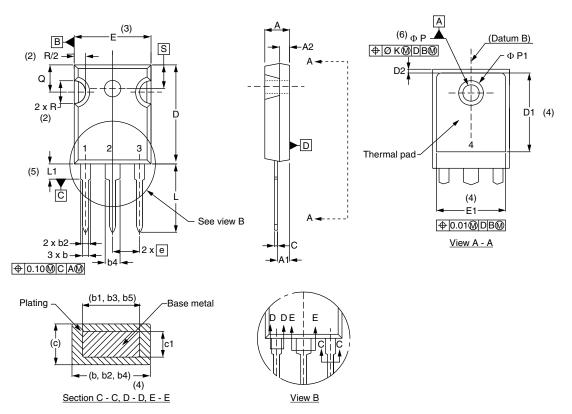
| LINKS TO RELATED DOCUMENTS | | | | | |
|--|-------------|--------------------------|--|--|--|
| Dimensions <u>www.vishay.com/doc?95542</u> | | | | | |
| Down as a disconsistence of the same of th | TO-247ACPbF | www.vishay.com/doc?95226 | | | |
| Part marking information | TO-247AC-N3 | www.vishay.com/doc?95007 | | | |



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TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



| SYMBOL | MILLIMETERS | | INC | NOTES | |
|---------|-------------|-------|-------|-------|-------|
| STWIDGE | MIN. | MAX. | MIN. | MAX. | NOTES |
| Α | 4.65 | 5.31 | 0.183 | 0.209 | |
| A1 | 2.21 | 2.59 | 0.087 | 0.102 | |
| A2 | 1.17 | 1.37 | 0.046 | 0.054 | |
| b | 0.99 | 1.40 | 0.039 | 0.055 | |
| b1 | 0.99 | 1.35 | 0.039 | 0.053 | |
| b2 | 1.65 | 2.39 | 0.065 | 0.094 | |
| b3 | 1.65 | 2.34 | 0.065 | 0.092 | |
| b4 | 2.59 | 3.43 | 0.102 | 0.135 | |
| b5 | 2.59 | 3.38 | 0.102 | 0.133 | |
| С | 0.38 | 0.89 | 0.015 | 0.035 | |
| c1 | 0.38 | 0.84 | 0.015 | 0.033 | |
| D | 19.71 | 20.70 | 0.776 | 0.815 | 3 |
| D1 | 13.08 | - | 0.515 | - | 4 |

| SYMBOL | MILLIN | IETERS | INC | NOTES | |
|---------|----------|--------|-----------|-------|-------|
| STWIDOL | MIN. | MAX. | MIN. | MAX. | NOTES |
| D2 | 0.51 | 1.35 | 0.020 | 0.053 | |
| E | 15.29 | 15.87 | 0.602 | 0.625 | 3 |
| E1 | 13.46 | - | 0.53 | 1 | |
| е | 5.46 BSC | | 0.215 BSC | | |
| ØK | 0.254 | | 0.0 | 0.010 | |
| L | 14.20 | 16.10 | 0.559 | 0.634 | |
| L1 | 3.71 | 4.29 | 0.146 | 0.169 | |
| ØΡ | 3.56 | 3.66 | 0.14 | 0.144 | |
| Ø P1 | - | 7.39 | - | 0.291 | |
| Q | 5.31 | 5.69 | 0.209 | 0.224 | |
| R | 4.52 | 5.49 | 0.178 | 0.216 | |
| S | 5.51 BSC | | 0.217 BSC | | |
| | · | | · | | · |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q

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